

TIDA-00685

J1

C1

R3

U1

R2

C2

R1

J2

ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: TIDA-00685

REV: E1

SUN REV: Not In VersionControl

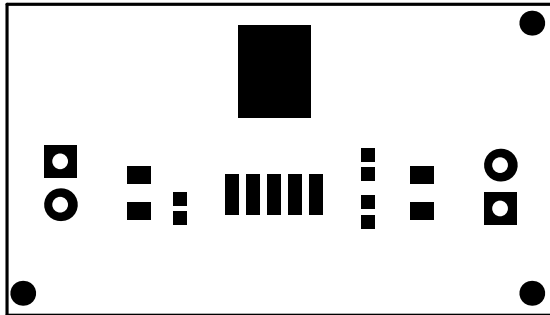
LAYER NAME = Top Overlay

TID #: TIDA-00685

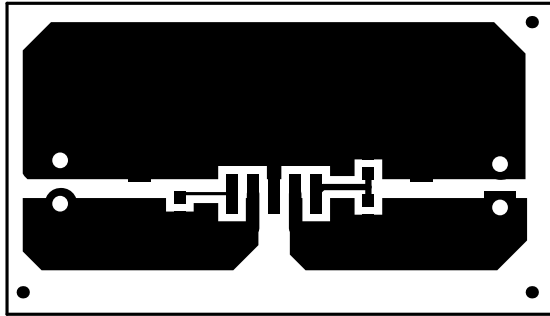
PLOT NAME = Top Overlay

GENERATED : 9/24/2015 1:53:56 PM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00685	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-00685		
PLOT NAME = Top Solder Mask	GENERATED : 9/24/2015 1:53:57 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00685	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-00685		
PLOT NAME = Top Layer	GENERATED : 9/24/2015 1:53:57 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00685	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-00685		
PLOT NAME = Bottom Layer	GENERATED : 9/24/2015 1:53:58 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: TIDA-00685

REV: E1

SUN REV: Not In VersionControl

LAYER NAME = Bottom Solder

TID #: TIDA-00685

PLOT NAME = Bottom Solder Mask

GENERATED : 9/24/2015 1:53:59 PM

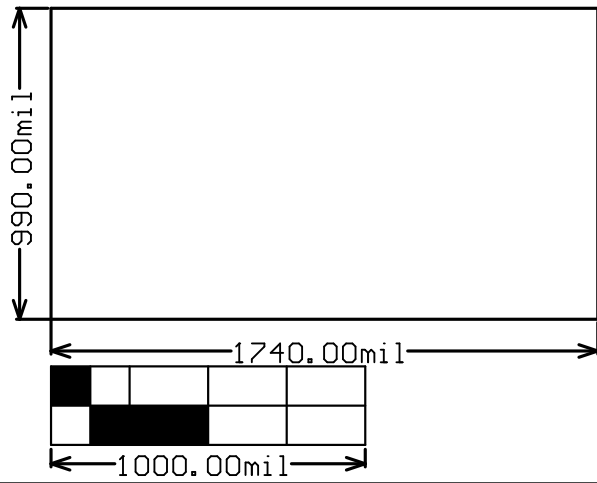
TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00685	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-00685		
PLOT NAME = Bottom Overlay	GENERATED : 9/24/2015 1:53:59 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00685	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-00685		
PLOT NAME = Drill Drawing	GENERATED : 9/24/2015 1:54:00 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00685	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-00685		
PLOT NAME = Board Dimensions	GENERATED : 9/24/2015 1:54:01 PM		TEXAS INSTRUMENTS



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